### IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor:	John H. Magerlein et al.	Date:	November 14, 2003		
Application No.:		Examiner:			
Filed:	Herewith	Art Unit:			
Title:	Method of Manufacture of Silicon Based Package and Devices Manufactured Thereby	Attorney:	Graham S. Jones, II 42 Barnard Avenue Poughkeepsie, NY 12601-5023		

### **INFORMATION DISCLOSURE STATEMENT**

Commissioner for Patents P.O. Box 1450 Alexandria VS, 22313-1450

Sir:

Pursuant to the duty of disclosure set forth in 37 CFR 1.56, and further pursuant to 37 CFR 1.97 and 37 CFR 1.98, Applicants hereby respectfully submit copies of the following prior patents and publications as listed on Form PTO-1449, attached hereto.

Respectfully submitted, John H. Magerlein et al.

By:

Graham S. Jones, II, Attorney

Registration No. 20,429 Telephone: 845-473-9118 Facsimile: 845-485-9399

Enclosures: Form 1449 with references attached

FORM PTO-1449 (M dified)

#### LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE STATEMENT

(Use several sheets if necessary)

**Attorney Docket Number:** 

FIS9-2000-0412-US2

Serial Number

APPLICANT: John H. Magerlein et al.

Filing Date:

Group:

Examiner Initials		Document Number	Issued Date	Name	Class	Subclass	FILING DATE
	AA	5,258,236	2 Nov. 1993	Arjavalingam	428	626	(IF APPRO.)
	AB	5,497,545	12 Mar. 1996	Watanabe	29	830	
	AC	5,654,590	5 Aug. 1997	Kuramochi	257	778	
	AD	5,965,933	12 Oct. 1999	Young	257	621	
	AE	6,036,809	14 Mar. 2000	Kelly	156	247	
	AF	6,066,562	23 May 2000	Oshima	438	691	
	AG	6,184,060	6 Feb. 2001	Siniaguine	438	106	
	AH	6,187,418	13 Feb. 2001	Fasano	428	210	

Application No. Date Name Class Subclass		70.000					•
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1 territorial de la constante		Application No.	Date	Name	Class	Subclass	
AI US2002/0086519A1 4 Jul 2002 July 400	$\mathbf{A}^{-}$	I US2002/0086519A1	4 I 1 2002		+		
A1 032002/0086519A1 4 Jul. 2002 Houston 438 622			4 Jul. 2002	Houston	438	622	

## FOREIGN PATENT DOCUMENTS

A	 ment nber	Date	Country	Class	Subclass	Transl Yes	ation No
			J	<u> </u>			

# OTHER ART (Including Author, Title, Date, Pertinent Pages, etc.)

AK Matsuo et al. "Silicon Interposer Technology for High-density Package", Session 36, Afternoon, Wednesday, May 24, 2000, at Caesar's Palace, Las Vegas, NV, Proceedings of IEEE Electronic Components and Technology Conference, IEEE, ISBN 0780359089, 4 pages (2000)

### **EXAMINER**

DATE CONSIDERED

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.